



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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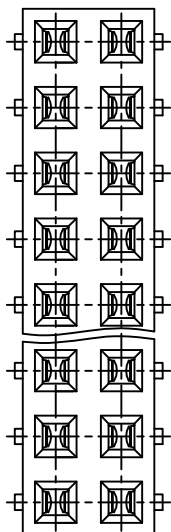
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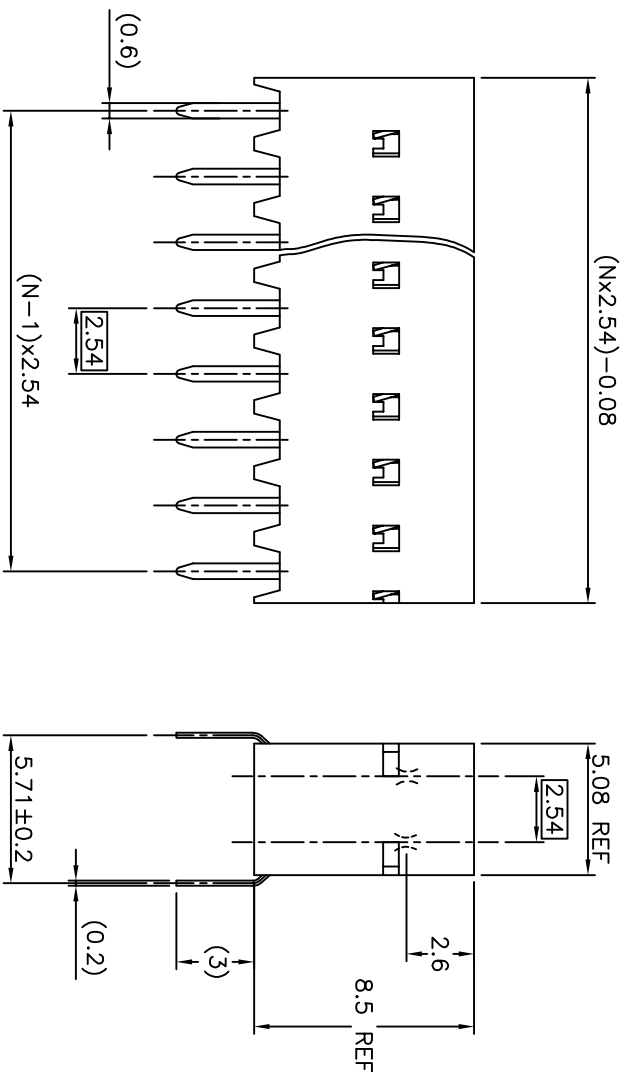
PRODUCT NUMBER  
89892-YXXLF

RoHS COMPATIBLE, SEE NOTE 5  
NUMBER OF POSITIONS PER ROW: 02 to 50  
PLATING CODE  
3 = 0.76µm GOLD ON CONTACT AREA.  
2µm MIN MATTE TIN ON TAIL.  
4 = 2µm MIN MATTE TIN FULL PLATED  
1.27µm Ni MIN UNDERPLATING

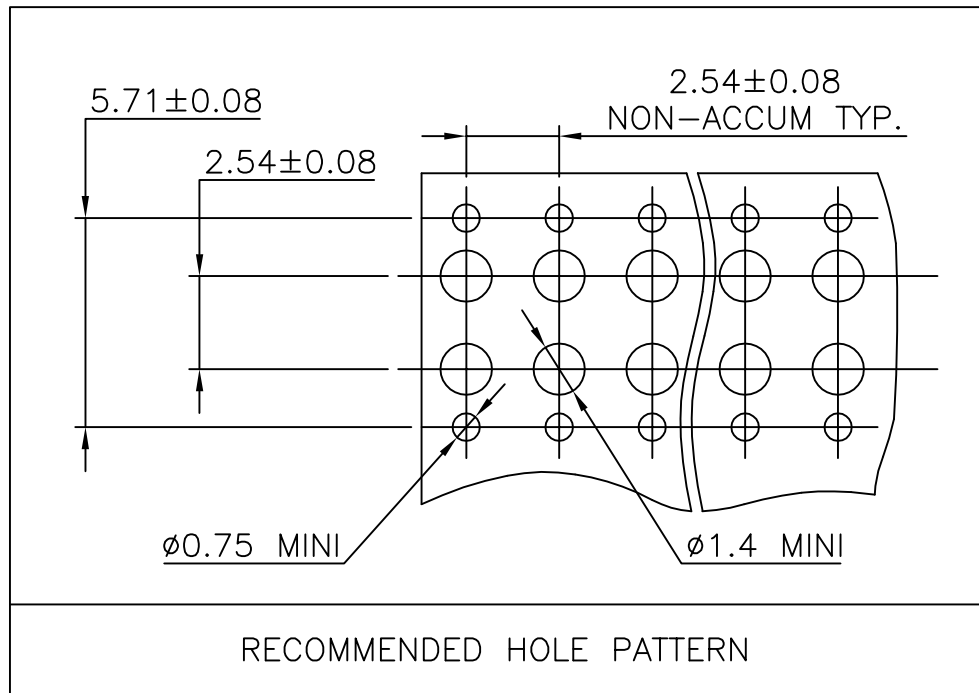


NOTES:

- 1 - HOUSING MAT'L: THERMOPLASTIC GLASS FILLED FLAME RETARDANT PER UL 94 V-0 COLOR: BLUE.
- 2 - TERMINAL MATERIAL : PHOSPHOR BRONZE.
- 3 - 02 UP TO 04 POSITIONS PRODUCT PACKED IN PLASTIC BOX. 05 UP TO 50 POSITIONS PRODUCT PACKED IN TUBE.
- 4 - TO DETERMINE DIMENSIONS :  
N = NUMBER OF POSITIONS PER ROW  
EXAMPLE: 8 POS: (Nx2.54)-0.08=20.24 mm
- 5 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS
  - a - PLATING:
    - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
  - b - MANUFACTURING PROCESS COMPATIBILITY
    - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
  - c - LABELING:
    - MEETS PACKAGING SPECS AS PER GS-14-920
  - d - LEGAL STATEMENT: SEE GS-47-0004

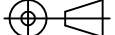




mat'l. code		surface		tolerance		projection		product family	
SEE NOTES		ISO 1302		ISO 406		ISO 1101		DUBOX	
lfr	ecn no	dr	date	tolerances unless otherwise specified		mm		title	
C	F80638	PNZ	98.10.14	linear		±0.3		BtB RECEPT.	
D	F10116	GC0	01.01.23	angles		scale 5:1		VERT DR TMT	
E	F04-0347	DLE	04.09.28	*Z*					
F	F06.0204	DLE	06.06.21	dr	D	LEGAND	04.09.28	dwg no	
G	B-19123	LMU	14.10.21	engr	P	NIZZI	04.09.28	sheet 1 of 2	
				chr	D	LEGAND	04.09.28	size	
				appt	P	NZ	04.09.28	A3	
sheet	revision	G	B					type	
index	sheet	1	2					CUSTOMER	
								Drawing	



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mat'l. code SEE SHEET 1				surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family DUBOX											
ltr	ecn no	dr	date	tolerances unless otherwise specified					title BtB RECEPT. VERT DR TMT												
A	F04-0347	DLE	04.09.28	angles	linear	±0.3															
B	F06-0204	DLE	06.06.21			±2'	scale 5:1														
				dr	D LEGRAND	04.09.28			dwg no						sheet 2 of 2			size			
				enr	P NIZZI	04.09.28			89892						A4						
				chr	D LE	04.09.28															
				appd	P NZ	04.09.28			type						CUSTOMER			Drawing			
sheet index		revision sheet																			